

Automotive 150 mA, 40 V tracking LDO with 5 mV tolerance Rev. 1 — 28 April 2025 Product data sheet

1. General description

The NEX91x15-Q100 is a Low-Dropout (LDO) voltagetracking regulator with high tracking accuracy of 5 mV (max) and excellent load and line transient responses. It is specifically designed to power off-board sensors in automotive applications such as power train, safety, and Body Control Modules (BCMs). The device supports a wide input voltage range from 4 V to 40 V (up to 45 V transient) to withstand cold-crank and loaddump transient conditions.

The device output tracks the reference voltage applied to the EN/ADJ pin with an accuracy of ± 5 mV over the specified temperature range for loads up to 150 mA. The high tracking accuracy ensures a precise power supply for off-board sensors and modules, improving the performance of radiometric sensors such as pressure and position sensors.

The device switches to standby mode by pulling down the EN/ADJ pin, which enables an ultra-low shutdown current of 0.75 μ A typical to extend battery life. The device integrates protection features such as battery reverse polarity protection (-42 V), output reverse current protection, output short-to-battery and ground protection, current limit, and thermal shutdown. These protections guard against the high risk of cable failures in an off-board power system. The power-good (PG) output indicates an over voltage or under voltage condition of the tracking output.

The device operates across a temperature range from -40 °C to 125 °C ambient and -40 °C to 150 °C junction. It is available with thermal enhanced package SOT8063-2 (HSO8).



Fig. 1. Typical application

2. Features and benefits

- AEC-Q100 qualified for automotive applications
 - Temperature grade 1 (T_{amb}): -40 °C to 125 °C
 - Junction temperature range (T_j): -40 °C to 150 °C
- Input voltage range: 4 V to 40 V
 - Absolute maximum input range: -42 V to 45 V
 - Wide output voltage range: 2 V to 40 V
 - Absolute maximum output range: -5 V to 45 V
- Tight output tracking tolerance: ±5 mV
- Maximum output current: 150 mA
- Low dropout voltage:
 - 220 mV typical at 150 mA (V_{OUT} = 5 V)
- Low quiescent current (I_Q):
 - 45 µA typical quiescent current at light loads
 - 0.75 µA typical shut-down current
- Over voltage and under voltage indication at PG output
- Active output discharge with a typical discharge current of 800 µA
- Stable with a wide range of ceramic output-stability cap:
 - ESR from 0.001 Ω to 5 $\Omega;$ output capacitor from 4.7 μF to 470 μF
- Integrated various fault protections:
 - · Reverse polarity protected input
 - Reverse current protection
 - Thermal shutdown
 - · Short-circuit to ground and battery protection
- Over-current protection
- HSO8 package available:
 - SOT8063-2 (HSO8): R_{θJA} = 47.5 °C/W

3. Applications

- Supply for off-board sensors
- · High precision voltage tracking
- Body Control Modules (BCMs)
- Power switch for off-board loads

Table 1. Device information

Part number	PG	Cable compensation
NEX91515PB-Q100	Y	N
NEX91615PB-Q100	N	Y

ne<mark>x</mark>peria

4. Ordering information

Table 2. Ordering information					
Type number					
Type number	Temperature range (T _j) Name Description		Description	Version	
NEX91515PB-Q100	-40 °C to 150 °C		Plastic, thermal enhanced small outline	0.0 .	
NEX91615PB-Q100	-40 °C to 150 °C	HSO8	SO8 package; 8 leads; 1.27 mm pitch; 4.9 mm × 3.9 mm × 1.7 mm body		

5. Marking

Table 3. Marking codes		
Type number	Marking code	
NEX91515PB-Q100	N91515	
NEX91615PB-Q100	N91615	

NEX91x15-Q100 Submit document feedback

6. Pin configuration and description

6.1. Pin configuration



6.2. Pin description

Table 4. Pin description

Symbol		1/0	Description	
F111	NEX91515	NEX91615	1/0	Description
1	OUT	Ουτ	0	Tracking output voltage pin. Place a capacitor as close to the output of the device as possible, follow the capacitance and ESR requirements described in <u>Table 8</u> .
2	NC	NC	I	Not connected pin. It is not connected internally and can be tied to the ground plane to enhance thermal dissipation.
3	GND	GND	G	Ground pin. This pin is connected to ground internally.
4	PG	FB	0	PG : power-good pin. It is an open-drain pin that must connect to positive voltage rail via an external pull-up resistor. V_{PG} is logic level high when V_{OUT} is above or lower the power-good threshold. If not used, can be left floating. FB : feedback pin. External resistor used to set the max cable comp voltage at full load current, there is no cable comp voltage when pull to out pin.
5	ADJ	EN/ADJ	1	ADJ : adjustable voltage pin, can be connected directly to the reference voltage or through a resistor divider for lower voltage. Place a capacitor close to the ADJ pin to eliminate line interference. For enable function, a low voltage signal disables the device, while a high voltage signal enables it. EN/ADJ : enable and adjustable voltage pin.
6	NC	GND	G	GND : ground pin. This pin is connected to ground internally. Not connected pin. It is not connected internally and can be tied to the ground plane to enhance thermal dissipation.
7	EN	NC	1	EN : enable pin. A low voltage signal disables the device, while a high voltage signal enables it. Not connected pin. It is not connected internally and can be tied to the ground plane to enhance thermal dissipation.
8	IN	IN	I	Input power-supply voltage pin. Place a small ceramic capacitor as close to the input of the device as possible to reduce line interference.
Expos	ed thermal p	ad	-	Not connected internally. It can be left floating, but for better thermal performance it is recommended to connect it to the GND.

7. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).[1]

Symbol	Parameter	Conditions	Min	Мах	Unit
V _{IN}	unregulated input voltage		-42	45	V
V _{OUT}	tracking output voltage		-5	45	V
V _{EN}	enable output voltage		-42	45	V
V _{ADJ}	adjustable voltage		-42	45	V
V _{FB}	feedback voltage		-5	45	V
V _{PG}	power good voltage		-0.3	6.6	V
Тj	operating junction temperature		-40	150	°C
T _{amb}	operating ambient temperature		-40	125	°C
T _{stg}	storage temperature		-65	165	°C

[1] Stresses beyond those conditions under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

8. ESD ratings

Table 6. ESD ratings

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V	electrostatic	HBM: ANSI/ESDA/JEDEC JS-001 class 3A [1]	-4000	-	4000	V
▼ESD	discharge voltage	CDM: ANSI/ESDA/JEDEC JS-002 class C3 [2]	-1000	-	1000	V

[1] HBM stress testing was performed in accordance with AEC-Q100-002.

[2] CDM stress testing was performed in accordance with AEC-Q100-011.

9. Thermal Information

Table 7. Thermal information

Thermal resistance according to JEDEC51-5 and -7.

Symbol	Parameter	SOT8063-2 (HSO8)	Unit
$R_{\theta JA}$	junction to ambient thermal resistance	47.5	°C/W
$R_{\theta JC(top)}$	junction to case (top) thermal resistance	78.8	°C/W
$R_{\theta JB}$	junction to board thermal resistance	22.8	°C/W
Ψ_{JT}	junction to top char parameter	9.5	°C/W

10. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{IN}	input voltage		4	-	40	V
V _{OUT}	output voltage		2	-	40	V
I _{OUT}	output current	[1]	-	-	150	mA
V _{ADJ}	adjust input voltage range (voltage tracking range)		2	-	40	V
V _{EN}	enable voltage		0	-	40	V
C _{IN}	input capacitance		0.47	1	-	μF
C _{OUT}	output capacitance	[2]	4.7	-	470	μF
ESR	output capacitor ESR requirements	[3]	0.001	-	5	Ω
T _{amb}	ambient temperature		-40	-	125	°C
Tj	junction temperature		-40	-	150	°C

Table 8. Recommended operating conditions

[1] Maximum output current when device is not thermal shutdown.

[2] The minimum output capacitance requirement is applicable for a worst-case capacitance tolerance of 30%.

[3] Relevant ESR value at f = 10 kHz, if using a large ESR capacitor it is recommended to decouple this with a 100 nF ceramic capacitor to improve transient performance.

11. Electrical characteristics

Table 9. Electrical characteristics

At recommended operating conditions; $T_j = -40$ °C to 150 °C; $C_{OUT} = 4.7 \ \mu$ F; $V_{IN} = 13.5 \ V$;

 I_{OUT} = 100 µA; V_{ADJ} = 5 V; (unless otherwise noted) voltages are referenced to GND (ground = 0 V).

Symbol	Paramotor	Conditions		T _{amb} =	-40 °C to	125 °C	Unit
Symbol	r al allietei			Min	Typ[1]	Мах	Onic
Power supply	/						
V _{IN}	input voltage range			4	-	40	V
		V _{IN} rising		-	3.6	3.9	V
V _{IN(UVLO)}	threshold	V _{IN} falling		-	3.2	3.5	V
		hysteresis		-	400	-	mV
	V _{IN}	V _{IN} = 5.5 V to 40 V;	NEX91615PB-Q100	-	45	70	
I_Q quiescent current $I_{OUT} = 100$ = 5 V	I _{OUT} = 100 μA; V _{ADJ} = 5 V	NEX91515PB-Q100	-	85	110	μA	
I _{GND}	ground current	$V_{IN} = 13.5 V;$ $I_{OUT} \le 150 \text{ mA}; V_{ADJ} = 5 V$ [2]		-	250	-	μA
I _{STD}	stand-by current	V _{IN} = 4 V to 40 V; V _{EN} ≥ 2 V; V _{ADJ} < 0.7 V		-	6.4	15	μA
I _{SHUT}	shutdown current	V _{IN} = 4 V to 40 V; V _{EN} = 0 V		-	0.75	3.5	μA
I _{R(IN)}	reverse current at IN	V _{IN} = 0 V; V _{OUT} = 40 V; V _{ADJ} = 5 V		-5	-	0	μA
I _{R(-IN)}	reverse current at negative IN	V _{IN} = -40 V; V _{OUT} = 0	V; V _{ADJ} = 5 V	-10	-	0	μA

Symbol	Deremeter	Conditions		Conditions T _{amb} = -40 °C t		125 °C	Unit
Symbol	Parameter	Conditions		Min	Typ[1]	Мах	Unit
EN/ADJ and I	B pin	,					
V _{EN_L}	logic input low level			-	-	0.7	V
V _{EN_H}	logic input high level			2	-	-	V
I _{EN}	EN pin current	V _{IN} = 13.5 V; V _{EN} = 5	V	-	-	100	nA
V _{ADJ_H}	adjust high signal valid	$ V_{OUT} - V_{ADJ} \le 5 \text{ mV}$		1.8	-	-	V
V _{ADJ_L}	adjust low signal valid	V _{OUT} = 0 V		-	-	0.7	V
I _{ADJ}	adjust input current	V _{IN} = 13.5 V; V _{EN} = V _{ADJ} = 5 V	NEX91515PB-Q100 NEX91615PB-Q100	-	-	600 800	nA
Іср	FB pin current	$V_{ADI} = V_{EB} = 5 V$			-	5	μA
	· - p ca c	ADJ PB CT				•	F ^m , 1
V _{OUT}	output accuracy	V _{IN} = 1 V + V _{OUT} to 40 100 µA to 150 mA	0 V (V _{IN} ≥ 4 V; I _{OUT} =	-5	-	5	mV
$\Delta V_{OUT(\Delta VIN)}$	line regulation	V _{IN} = 5.5 V to 40 V; I _C	_{DUT} = 10 mA; V _{ADJ} = 5 V	-	-	0.5	mV
ΔV _{OUT(ΔΙΟUT)}	load regulation	V _{IN} = 6 V to 40 V; I _{OU} V _{ADJ} = 5 V	_T = 100 μA to 150 mA;	-	-	2	mV
\ <i>\</i>	drama ut valta da	$V_{DO} = V_{IN} - V_{OUT};$	I _{OUT} = 100 mA	-	145	240	
VDO	dropout voltage	$V_{IN} = V_{ADJ} = 5 V$	I _{OUT} = 150 mA	-	220	350	mv
I _{OUT}	output current	V _{IN} = V _{ADJ} + 1 V		-	-	150	mA
I _{DIS}	discharge current	V _{OUT} = 5 V; V _{IN} = 13.8	5 V	-	800	-	μA
I _{CL}	output current limit	V _{IN} = 13.5 V; output s	hort to 90% x V _{ADJ}	180	420	600	mA
PSRR	power-supply ripple rejection	V _{IN} = 13.5 V; V _{ADJ} = 5 C _{OUT} = 4.7 μF; freque	5 V; I _{OUT} = 10 mA; ency = 100 Hz [2]	-	85	-	dB
V _n	output noise voltage	V _{ADJ} = 5 V; I _{OUT} = 1 n BW = 10 Hz to 100 kH	nA; Iz; 5 μVRMS reference ^[3]	-	50	-	μVRMS
Power-good							
V _{PG (UV)}	power-good switching threshold; under- voltage	V _{OUT} decreasing; pow low; V _{OUT} - V _{ADJ}	ver-good from high to	-220	-130	-50	mV
V _{PG (OV)}	power-good switching threshold; over-voltage	V _{OUT} increasing; power low; V _{OUT} - V _{ADJ}	er-good from high to	50	130	220	mV
t _{PG_R}	power-good reaction time			-	15	40	μs
t _{PG_D}	power-good deglitch time			-	250	470	μs
V _{PG_L}	PG pin low level output voltage	sink 1 mA current		-	0.2	0.4	V
I _{PG}	power-good output leakage current	V _{IN} = 13.5 V; V _{PG} = 5 V		-	-	100	nA
Operating temperature range							
T _{SD}	junction thermal shutdown temperature	rising junction temperature [2]		-	175	-	°C
T _{HYST}	thermal shutdown hysteresis	[2]		-	20	-	°C

[1] All typical values are measured at T_{amb} = 25 °C. [2] Guaranteed by bench test, not fully tested in production.

[3] Guaranteed by design.



12. Typical characteristics

At recommended operating conditions, voltages are referenced to GND (ground = 0 V), and typical values are at 25 °C (unless otherwise noted).





NEX91x15-Q100

© Nexperia B.V. 2025. All rights reserved

Product data sheet

Automotive 150 mA, 40 V tracking LDO with 5 mV tolerance



Automotive 150 mA, 40 V tracking LDO with 5 mV tolerance



NEX91x15-Q100

Automotive 150 mA, 40 V tracking LDO with 5 mV tolerance



NEX91x15-Q100

Automotive 150 mA, 40 V tracking LDO with 5 mV tolerance



NEX91x15-Q100 Submit document feedback

13. Detailed description

13.1. Overview

The NEX91x15-Q100 is a Low-Dropout (LDO) tracking regulator with ultra-low tracking tolerance and out. It is designed to supply off-board systems, such as sensors in powertrain or passive safety applications. The device offers multiple protection features, including reverse polarity protection and safeguards against shorts to the battery and ground. In addition, this device also features thermal shutdown protection in case of an over temperature event.

13.2. Function block diagram

The NEX91x15-Q100 function block diagram is shown in Fig. 22.



13.3. Feature description

13.3.1. Tracking output (V_{OUT})

The output voltage precisely follows the reference voltage applied to the ADJ input. This supports output voltage up to 40 V and current up to 150 mA. When the ADJ pin voltage exceeds the enable threshold voltage, the output begins rising to match the ADJ voltage. The output then increases linearly based on three factors: load conditions, output capacitance, and current limit. Once the output voltage reaches the ADJ pin voltage level, it stops rising and remains stable within ±5 mV of the reference voltage.

NEX91x15-Q100

© Nexperia B.V. 2025. All rights reserved

13.3.1.1. Output voltage equal to reference voltage

As shown in Fig. 23, the output voltage of the LDO output voltage is equal to the reference voltage within a tolerance of ± 5 mV. This is achieved by directly applying an external reference voltage to the ADJ pin, while the FB pin (NEX91615-Q100 only) is connected to OUT pin. The output voltage can be expressed as: V_{OUT} = V_{REF}.



13.3.1.2. Output voltage less than the reference voltage

As shown in Fig. 24, the LDO output voltage can achieve lower output voltage than the reference voltage. The output voltage was to be approximately $V_{REF} \times R^2$



13.3.1.3. Output voltage larger than the reference voltage

In practical applications, the output of the tracker is used to supply power to the off-board load through a cable. The equivalent resistance of the cable gives rise to a voltage drop, which may result in an inadequate power supply for the offboard load. This problem can be mitigated by implementing cable compensation strategies to counteract the voltage drop occurring within the cable.

NEX91x15-Q100

13.3.1.3.1. Fixed cable compensation

An external resistive divider connected between the OUT and FB pins can be configured to generate an output voltage exceeding the reference voltage (ADJ), as illustrated in the Fig. 25. The output voltage is defined by: $V_{PRP} \times (R1 + R2)$

$$V_{OUT} = \frac{V_{REF} \times (R1 + R2)}{R2}$$

R1 and R2 should ideally be in the range of 10 k Ω to 100 k Ω .



13.3.2. Undervoltage Lockout (UVLO)

An undervoltage lockout (UVLO) circuit is to stop the operation of the device when the input voltage falls below the typical threshold $V_{IN(UVLO)}$. The UVLO circuit includes hysteresis to prevent the device from shutting down if input voltage drops briefly after power up, as specified in the <u>Electrical Characteristics table</u>. If the input voltage experiences a negative transient that drops below the UVLO threshold and then recovers, the regulator will shut down and restart following the normal power-up sequence once the input voltage exceeds the required level.

13.3.3. Current limit operation

The device features an internal current limit circuit that protects the regulator during transient high-load current faults or shorting events. When the device is in current limit mode, the output voltage is not regulated. During a current limit event, the device heats up due to increased power dissipation. When the device reaches the current limit (I_{CL}), the pass transistor dissipates power according to the formula [($V_{IN} - V_{OUT}$) x I_{CL}]. If thermal shutdown is triggered, the device will turn off. Once it cools down, the internal thermal shutdown circuit will turn the device back on. If the output current fault condition persists, the device will cycle between current limit and thermal shutdown.

13.3.4. Thermal protection

The NEX91x15-Q100 integrates an internal temperature sensor to monitor the junction temperature (T_j). If the T_j exceeds the thermal shutdown temperature (T_{SD}) of 175 °C, the device ceases operation. The device will resume functioning when T_j drops below the hysteresis threshold of approximately 20 °C.

Thermal shutdown may be triggered during start-up due to large inrush currents charging substantial output capacitance, or under heavy loads where high ($V_{IN} - V_{OUT}$) regulations result in significant power dissipation across the die. Proper heat sinking should be considered in these high-power dissipation scenarios.

13.3.5. Output short to battery and reverse protection

The NEX91x15-Q100 employs a back-to-back PMOS topology to protect the device from damage during fault conditions where V_{OUT} exceeds V_{IN} , effectively blocking reverse current flow. The device remains undamaged as long as it operates within the parameters provided in <u>Limiting values</u>. This integrated protection eliminates the requirement for an external diode.

The NEX91x15-Q100 remains undamaged, even when the output is shorted to the battery (see Fig. 26, with NEX91615-Q100 as the example). A short to the battery might occur when the device is powered by a lower separated input voltage supply as shown in Fig. 27. In this example, the input supply is set to 9 V. When a short to the battery (13.5 V typical) occurs on output that typically runs at 5 V, the continuous reverse current that flows out through the input is less than 5 μ A.



13.3.6. Active output discharge

The device incorporates an active output discharge function when enabled, ensuring the output voltage rapidly returns to its nominal level during over-voltage fluctuations. This is particularly effective during load transients such as heavy-to-light load transitions. When the output voltage exceeds the nominal level, the device activates a FET that connects a resistor with a resistance value of several thousand ohms in series with the ground to achieve active discharge. Under these conditions, the output sources a typical current of 800 μ A (at an output voltage of 5 V) through this resistance network, even without an external load.

13.3.7. Tracking output with an enable circuit

For the NEX91615-Q100 device, the EN pin functions together with ADJ pin, it cannot control separately via EN pin. Separating the enable function can be achieved using a circuit such as that referenced in Fig. 28.

When the input voltage at the EN/ADJ pin falls below the 0.7 V threshold, the NEX91615-Q100 is disabled and enters a sleep mode, drawing only 0.75 µA from the power supply. In typical applications, the reference voltage is often sourced from another regulator (such as a DC-DC converter or LDO voltage rail). This setup allows flexible enable/disable control via external I/O and circuitry, as shown in Fig. 28. In this example, the NEX90230-Q100, a 150 mA LDO with ultra-low quiescent current, serves as both the reference voltage source for the NEX91615-Q100 and as a power supply to the ADC.

Automotive 150 mA, 40 V tracking LDO with 5 mV tolerance



13.3.8. Power-good (PG)

The power-good (PG) output signals an over-voltage or under-voltage condition on the tracking output by comparing the output voltage (V_{OUT}) against the external reference voltage (V_{ADJ}). When output voltage variations exceed the defined PG switching thresholds, it will be indicated by a low-level signal at the PG output. Transient events shorter than the power-good reaction time (t_{PG_R}) will not activate the PG output. The PG deglitch time (t_{PG_D}) provides a start-up window for MCU or oscillators, representing the interval between threshold crossings and the PG output transitioning from low to high. This open-drain output requires the implementation of a pull-up resistor to a positive voltage rail.

Table 10 summarizes the PG response characteristics under various operating conditions.

Device state		PG logic status			
Device state		High impedance	Low impedance		
Enable (EN = High)	V _{OUT} - V _{ADJ} < V _{PG (UV)} V _{OUT} - V _{ADJ} > V _{PG (OV)}		\checkmark		
Shutdown (EN = Low)			\checkmark		
Thermal shutdown	T _j > T _{SD}				
V _{IN(UVLO)}	V _{IN} < 0.7 V	\checkmark			

Table 10. PG pin logic table

13.4. Application implementation

13.4.1. Design requirements

A typical application is applied in automotive and power supply for an off-board sensor or multi sensor, which normally requires 5 V or 3.3 V output. The design parameters are specified in <u>Table 11</u>.

lable 11. Design parameters		
Parameters	Value	
Input voltage	4 V to 40 V	
ADJ reference voltage	2 V to 20 V	
Output voltage	2 V to 20 V	
Output current	150 mA max	
Output capacitor range	4.7 μF to 470 μF	
Output capacitor ESR range	1 mΩ to 5 Ω	

All information provided in this document is subject to legal disclaimers.

13.4.2. Typical application



13.4.2.1. Detailed design procedure

To begin the design process, determine the following requirements.

- Operation input voltage range
- Reference voltage
- Output voltage
- Output current rating
- Input capacitor
- Output capacitor

13.4.2.1.1. Input capacitor

The NEX91x15-Q100 recommends an input decoupling capacitor connected from IN to GND and close to the IC terminals through is not required for stability, the value of which depends on the end-applications. The input supplies have a high impedance in some applications, thus placing the input capacitor on the input supply helps reduce the input impedance.

In addition, the input capacitor counteracts reactive input sources and improves transient response, input ripple, and PSRR. Several input capacitors can be placed in parallel to lower the impedance over frequency if the supply has a high impedance over a larger range of frequencies noise. The bigger-value input capacitors are recommended when larger, fast rising time load/line transient is anticipated, or larger distance is located from input power supply source.

The voltage rating of input capacitors must be greater than the maximum input voltage.

13.4.2.1.2. Output capacitor

To ensure the stability of the NEX91x15-Q100, the device requires:

- An output capacitor with a capacitance range of 4.7 μF to 470 μF (with a 30% derating applied under worst-case conditions) should be connected between the OUT and GND terminals.
- ESR range between 0.001 Ω and 5 Ω .

It is recommended to select X7R and X5R type ceramic capacitors with low ESR to improve the load transient response and ripple performance.

14. Layout

14.1. Layout guidelines

For best overall performance, the following guidelines for LDO layout are recommended:

- Place all circuit components on the same side of the circuit board and as near as practical to the respective LDO pin connections.
- Place ground return connections to the input and output capacitor, and to the LDO ground pin as close as possible to each other, connected by a wide, component-side, copper surface.
- The use of vias and long traces to the input and output capacitors is strongly discouraged and negatively affects system performance.
- In most applications, the ground plane is necessary to meet thermal requirements.

A ground reference plane either embedded in the PCB itself or located on the bottom side of the PCB opposite the components. This reference plane serves to assure accuracy of the output voltage, shield noise, and behaves similarly to a thermal plane to spread (or sink) heat from the LDO device when connected to the thermal pad.

14.2. Layout examples

The figure below draws the layout example of NEX91615-Q100 device.



NEX91x15-Q100

15. Package outline



HSO8: Plastic, thermal enhanced small outline package; 8 leads;

Fig. 31. Package outline SOT8063-2 (HSO8)

16. Abbreviations

Table 12. Abbreviations				
Acronym	Description			
AEC	Automotive Electronics Council			
ANSI	American National Standards Institute			
CDM	Charged Device Model			
ESDA	ElectroStatic Discharge Association			
НВМ	Human Body Model			
IC	Integrated Circuit			
JEDEC	Joint Electron Device Engineering Council			
PG	Power-good			
UVLO	Under-Voltage LockOut			

17. Revision history

Table 13. Revision history							
Document ID	Release date	Data sheet status	Change notice	Supersedes			
NEX91X15_Q100 v. 1	20250428	Product data sheet	-	-			

18. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

 Please consult the most recently issued document before initiating or completing a design.

- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <u>https://www.nexperia.com</u>.

Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. Nexperia does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local Nexperia sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between Nexperia and its customer, unless Nexperia and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the Nexperia product is deemed to offer functions and qualities beyond those described in the Product data sheet.

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia takes no responsibility for the content in this document if provided by an information source outside of Nexperia.

In no event shall Nexperia be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, Nexperia's aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of Nexperia.

Right to make changes — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use in automotive applications — This Nexperia product has been qualified for use in automotive applications. Unless otherwise agreed in writing, the product is not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or

equipment, nor in applications where failure or malfunction of an Nexperia product can reasonably be expected to result in personal injury, death or severe property or environmental damage. Nexperia and its suppliers accept no liability for inclusion and/or use of Nexperia products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. Nexperia makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using Nexperia products, and Nexperia accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the Nexperia product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

Nexperia does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using Nexperia products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). Nexperia does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — Nexperia products are sold subject to the general terms and conditions of commercial sale, as published at <u>http://www.nexperia.com/profile/terms</u>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. Nexperia hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of Nexperia products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

Contents

2. Features and benefits	1. General description	1
3. Applications	2. Features and benefits	1
4. Ordering information	3. Applications	1
5. Marking	4. Ordering information	2
6. Pin configuration and description 3 6.1. Pin configuration 3 6.2. Pin description 3 7. Limiting values 4 8. ESD ratings 4 9. Thermal Information 4 10. Recommended operating conditions 5 11. Electrical characteristics 5 12. Typical characteristics 7 13. Detailed description 12 13.1. Overview 12 13.2. Function block diagram 12 13.3.1. Tracking output (V _{OUT}) 12 13.3.2. Undervoltage Lockout (UVLO) 14 13.3.3. Current limit operation 14 13.3.4. Thermal protection 14 13.3.5. Output short to battery and reverse protection 15 13.3.6. Active output discharge 15 13.3.7. Tracking output with an enable circuit 15 13.3.8. Power-good (PG) 16 13.4.1 Design requirements 16 13.4.2. Typical application 17 14. Layout 18 14.1. Layout guidelines 18 14.2. Layout examples 18 15. Package outline <td>5. Marking</td> <td>2</td>	5. Marking	2
6.1. Pin configuration 3 6.2. Pin description 3 7. Limiting values 4 8. ESD ratings 4 9. Thermal Information 4 10. Recommended operating conditions 5 11. Electrical characteristics 7 12. Typical characteristics 7 13. Detailed description 12 13.1. Overview 12 13.2. Function block diagram 12 13.3.1. Tracking output (V _{OUT}) 12 13.3.2. Undervoltage Lockout (UVLO) 14 13.3.3. Current limit operation 14 13.3.4. Thermal protection 14 13.3.5. Output short to battery and reverse protection 15 13.3.6. Active output discharge 15 13.3.7. Tracking output with an enable circuit 15 13.3.8. Power-good (PG) 16 13.4.1. Design requirements 16 13.4.2. Typical application 17 14. Layout guidelines 18 14.1. Layout examples 18 15. Package outline 19 16. Abbreviations 20 17. Revision history <	6. Pin configuration and description	3
6.2. Pin description	6.1. Pin configuration	3
7. Limiting values	6.2. Pin description	3
8. ESD ratings	7. Limiting values	4
9. Thermal Information 4 10. Recommended operating conditions 5 11. Electrical characteristics 5 12. Typical characteristics 7 13. Detailed description 12 13.1. Overview 12 13.2. Function block diagram 12 13.3. Feature description 12 13.3.1. Tracking output (V _{OUT}) 12 13.3.2. Undervoltage Lockout (UVLO) 14 13.3.3.3. Current limit operation 14 13.3.4. Thermal protection 14 13.3.5. Output short to battery and reverse protection 15 13.3.6. Active output discharge 15 13.3.7. Tracking output with an enable circuit 15 13.3.8. Power-good (PG) 16 13.4.1. Design requirements 16 13.4.2. Typical application 17 14. Layout guidelines 18 14.1. Layout guidelines 18 14.2. Layout examples 18 15. Package outline 19 16. Abbreviations 20 17. Revision history 20 18. Legal information 21	8. ESD ratings	4
10. Recommended operating conditions	9. Thermal Information	4
11. Electrical characteristics 5 12. Typical characteristics 7 13. Detailed description 12 13.1. Overview 12 13.2. Function block diagram 12 13.3. Feature description 12 13.3. Feature description 12 13.3. Feature description 12 13.3.1. Tracking output (V _{OUT}) 12 13.3.2. Undervoltage Lockout (UVLO) 14 13.3.3. Current limit operation 14 13.3.4. Thermal protection 14 13.3.5. Output short to battery and reverse protection 15 13.3.6. Active output discharge 15 13.3.7. Tracking output with an enable circuit 15 13.3.8. Power-good (PG) 16 13.4.1. Design requirements 16 13.4.2. Typical application 17 14. Layout 18 14.1. Layout guidelines 18 14.2. Layout examples 18 15. Package outline 19 16. Abbreviations 20 17. Revision history 20 18. Legal information 21	10. Recommended operating conditions	5
12. Typical characteristics 7 13. Detailed description 12 13.1. Overview 12 13.2. Function block diagram 12 13.3. Feature description 12 13.3. Feature description 12 13.3. Feature description 12 13.3. Feature description 12 13.3.1. Tracking output (V _{OUT}) 12 13.3.2. Undervoltage Lockout (UVLO) 14 13.3.3. Current limit operation 14 13.3.4. Thermal protection 14 13.3.5. Output short to battery and reverse protection 15 13.3.6. Active output discharge 15 13.3.7. Tracking output with an enable circuit 15 13.3.8. Power-good (PG) 16 13.4. Application implementation 16 13.4.1. Design requirements 16 13.4.2. Typical application 17 14. Layout guidelines 18 14.1. Layout examples 18 14.2. Layout examples 18 15. Package outline 19 16. Abbreviations 20 17. Revision history 20 18. Legal infor	11. Electrical characteristics	5
13. Detailed description	12. Typical characteristics	7
13.1. Overview	13. Detailed description	12
13.2. Function block diagram. 12 13.3. Feature description. 12 13.3.1. Tracking output (V _{OUT}). 12 13.3.2. Undervoltage Lockout (UVLO). 14 13.3.3. Current limit operation. 14 13.3.4. Thermal protection. 14 13.3.5. Output short to battery and reverse protection. 15 13.3.6. Active output discharge. 15 13.3.7. Tracking output with an enable circuit. 15 13.3.8. Power-good (PG). 16 13.4.1. Design requirements. 16 13.4.2. Typical application. 17 14. Layout guidelines. 18 14.1. Layout examples. 18 15. Package outline. 19 16. Abbreviations. 20 17. Revision history. 20 18. Legal information. 21	13.1. Overview	12
13.3. Feature description. 12 13.3.1. Tracking output (V _{OUT}). 12 13.3.2. Undervoltage Lockout (UVLO). 14 13.3.3. Current limit operation. 14 13.3.4. Thermal protection. 14 13.3.5. Output short to battery and reverse protection. 15 13.3.6. Active output discharge. 15 13.3.7. Tracking output with an enable circuit. 15 13.3.8. Power-good (PG). 16 13.4.1. Design requirements. 16 13.4.2. Typical application. 17 14. Layout 18 14.1. Layout guidelines. 18 14.2. Layout examples. 18 15. Package outline. 19 16. Abbreviations. 20 17. Revision history. 20 18. Legal information. 21	13.2. Function block diagram	12
13.3.1. Tracking output (V _{OUT})	13.3. Feature description	12
13.3.2. Undervoltage Lockout (UVLO)	13.3.1. Tracking output (V _{OUT})	12
13.3.3. Current limit operation. 14 13.3.4. Thermal protection. 14 13.3.5. Output short to battery and reverse protection. 15 13.3.6. Active output discharge. 15 13.3.7. Tracking output with an enable circuit. 15 13.3.8. Power-good (PG). 16 13.4.1. Design requirements. 16 13.4.2. Typical application. 17 14. Layout 18 14.1. Layout guidelines. 18 15. Package outline. 19 16. Abbreviations. 20 17. Revision history. 20 18. Legal information. 21	13.3.2. Undervoltage Lockout (UVLO)	14
13.3.4. Thermal protection. 14 13.3.5. Output short to battery and reverse protection. 15 13.3.6. Active output discharge. 15 13.3.7. Tracking output with an enable circuit. 15 13.3.8. Power-good (PG). 16 13.4. Application implementation. 16 13.4.1. Design requirements. 16 13.4.2. Typical application. 17 14. Layout guidelines. 18 14.1. Layout examples. 18 15. Package outline. 19 16. Abbreviations. 20 17. Revision history. 20 18. Legal information. 21	13.3.3. Current limit operation	14
13.3.5. Output short to battery and reverse protection	13.3.4. Thermal protection	14
13.3.6. Active output discharge. 15 13.3.7. Tracking output with an enable circuit. 15 13.3.7. Tracking output with an enable circuit. 15 13.3.8. Power-good (PG). 16 13.4. Application implementation. 16 13.4.1. Design requirements. 16 13.4.2. Typical application. 17 14. Layout 18 14.1. Layout guidelines. 18 14.2. Layout examples. 18 15. Package outline. 19 16. Abbreviations. 20 17. Revision history. 20 18. Legal information. 21	13.3.5. Output short to battery and reverse protection	15
13.3.7. Tracking output with an enable circuit. 15 13.3.8. Power-good (PG). 16 13.4. Application implementation. 16 13.4.1. Design requirements. 16 13.4.2. Typical application. 17 14. Layout. 18 14.1. Layout guidelines. 18 14.2. Layout examples. 18 15. Package outline. 19 16. Abbreviations. 20 17. Revision history. 20 18. Legal information. 21	13.3.6. Active output discharge	15
13.3.8. Power-good (PG)	13.3.7. Tracking output with an enable circuit	15
13.4. Application implementation	13.3.8. Power-good (PG)	16
13.4.1. Design requirements. 16 13.4.2. Typical application. 17 14. Layout. 18 14.1. Layout guidelines. 18 14.2. Layout examples. 18 15. Package outline. 19 16. Abbreviations. 20 17. Revision history. 20 18. Legal information. 21	13.4. Application implementation	16
13.4.2. Typical application	13.4.1. Design requirements	16
14. Layout 18 14.1. Layout guidelines 18 14.2. Layout examples 18 15. Package outline 19 16. Abbreviations 20 17. Revision history 20 18. Legal information 21	13.4.2. Typical application	17
14.1. Layout guidelines	14. Layout	18
14.2. Layout examples	14.1. Layout guidelines	18
15. Package outline	14.2. Layout examples	18
16. Abbreviations	15. Package outline	19
 Revision history20 Legal information21 	16. Abbreviations	20
18. Legal information21	17. Revision history	20
	18. Legal information	21

© Nexperia B.V. 2025. All rights reserved

For more information, please visit: http://www.nexperia.com For sales office addresses, please send an email to: salesaddresses@nexperia.com Date of release: 28 April 2025